

Description

The XU devices are low phase noise quartz-based PLL oscillators supporting a large range of frequencies and output interface types. These devices are designed to operate at three different power supplies and are available in multiple package sizes as well as temperature grades.

With a patented one-time program (OTP) allowing for infinite memory shelf life, the XU devices can be programmed to generate an output frequency from 16kHz to 1500MHz with a resolution as low as 1Hz accuracy. The configuration capability of this family of devices allows for fast delivery times for both sample and large production orders.

Pin Assignments

NOTE: To minimize power supply line noise, a $0.01\mu F$ bypass capacitor should be placed between V_{DD} (Pin 6) and GND (Pin 3).

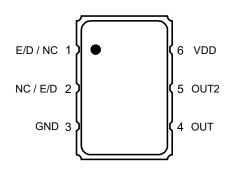


Table 1. Pin Description

Pin#	Name	Description
1	E/D NC	Enable/Disable ^{[a][b]} No connect
2	NC E/D	No connect Enable/Disable [a][b]
3	GND	Connect to ground
4	OUT	Output
5	OUT2	Complementary output ^[c]
6	V_{DD}	Supply voltage

- [a] Pulled high internally = output enabled.
- [b] Low = output disabled.
- [c] Do not connect for LVCMOS. For XLVCMOS both OUT and OUT2 are ON and in opposite phase.

See Ordering Information for more details.

Features

- Frequency range: 0.016MHz to 1500MHz^[1]
- Output types: LVDS, LVPECL, HCSL, LVCMOS
- Supply voltage options: 1.8V, 2.5V, or 3.3V
- Phase jitter (1.875MHz to 20MHz): 100fs typical
- Phase jitter (12kHz to 20MHz): 300fs typical
- Package options:
 - 5.0 × 3.2 × 1.2 mm
 - 7.0 × 5.0 × 1.3 mm
- Operating temperature: -20°C to +70°C
 - Frequency stability options: ±20, ±25, ±50, or ±100 ppm
- Operating temperature: -40°C to +85°C
 - Frequency stability options: ±25, ±50, or ±100 ppm
- Operating temperature: -40°C to +105°C
 - Frequency stability options: ±50 or ±100 ppm

^[1] There is a dead zone between 1037.5MHz to 1300MHz. Contact support for frequencies above 1300MHz.



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the device. The ratings, which are standard values for Renesas commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Table 2. Absolute Maximum Ratings

Item	Rating					
V_{DD}	-0.5 to +5.0V	-0.5 to +5.0V				
E/D	-0.5V to V _{DD} + 0.5V					
OUT	-0.5V to V _{DD} + 0.5V	-0.5V to V _{DD} + 0.5V				
Storage Temperature	-55°C to 125°C	-55°C to 125°C				
Maximum Junction Temperature	125°C					
Core Current	65mA maximum					
Theta J _A	JU6	75.9 °C/W	JS6	89.6 °C/W		
Theta J _B	- 300	48.6°C/W	- 100	54.3 °C/W		

ESD Compliance

Table 3. ESD Compliance

Human Body Model (HBM)	1000V
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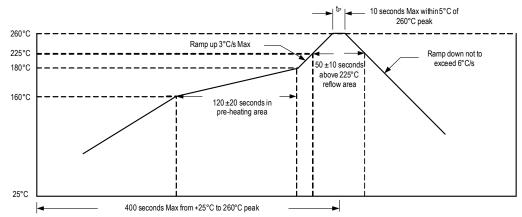
Mechanical Testing

Table 4. Mechanical Testing *

Parameter	Test Method
Mechanical Shock	Half-sine wave with 0.3ms 3000G. X, Y, Z each direction 1 time.
Mechanical Vibration	Frequency: 10 – 55MHz amplitude: 1.5mm. Frequency: 55 – 2000Hz peak value: 20G. Duration time: 4H for each X,Y,Z axis; total 12hours.
High Temp Operating Life (HTOL)	2000 hours at 125°C (under power).
Hermetic Seal	Gross leak (air leak test). Fine leak (Helium leak test) He-pressure: 6kgf/cm² 2 hours.

^{*} MSL level does not apply.

Solder Reflow Profile





DC Electrical Characteristics

Note for all DC Electrical Characteristics tables: A pull-up resistor from V_{DD} to E/D enables output when pin 1 is left open.

Table 5. 3.3V IDD DC Electrical Characteristics

 V_{DD} = 3.3V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Output Type	Conditions	Minimum	Typical	Maximum	Units
		LVDO	0.016MHz to 400MHz.			97	
		LVDS	400.000+MHz to 1.5GHz.			122	
	Current Consumption	nt Consumption	0.016MHz to 212.5MHz.			115	
			212.5+MHz to 400MHz.			128	 ∧
I _{DD}			400+MHz to 670MHz.			142	mA
		HCSL	0.016MHz to 670MHz.			145	
		17/04/00	0.016MHz to 62.5MHz.			98	
		LVCMOS	62.5+MHz to 167MHz.			108	

Table 6. 2.5V IDD DC Electrical Characteristics

 V_{DD} = 2.5V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Output Type	Conditions Minimum Typical		Maximum	Units	
		LVDS	0.016MHz to 400MHz.			90	
		LVDS	400.000+MHz to 1.35GHz.			103	
			0.016MHz to 156.25MHz.			102	
	I _{DD} Current Consumption	nption HCSL LVCMOS	156.25+MHz to 400MHz.			112	
			400+MHz to 670MHz.			118	mA
'DD			0.016MHz to 400MHz.			102	IIIA
			400.000+MHz to 670MHz.			112	
			0.016MHz to 62.5MHz.			80	
			62.5+MHz to 125MHz.			85	
			125+MHz to 167MHz.			92	



Table 7. 1.8V IDD DC Electrical Characteristics

 V_{DD} = 3.3V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Output Type	Conditions	Minimum	Typical	Maximum	Units	
		LVDS	0.016MHz to 400MHz.			65		
		LVDS	400.000+MHz to 1.0GHz.			72		
	Current Consumption	LVPECL	0.016MHz to 250MHz.			75		
I _{DD}			250.000+MHz to 670MHz.			97	mA	
		110	ПССІ	0.016MHz to 400MHz.			68	
		HCSL	400.000+MHz to 670MHz.			77		
		LVCMOS	0.016MHz to 125MHz.			58		

Table 8. LVDS DC Electrical Characteristics

 V_{DD} = 3.3V, 2.5V, 1.8V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C. Below are guaranteed for listed standard frequencies.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V _{OD}	Differential Output Voltage		0.25	0.4	0.5	
V _{OS}	Output Offset Voltage		1	1.17	1.375	W
V _{IH}	Enable/Disable Input High Voltage		70%V _{DD}			V
V _{IL}	Enable/Disable Input Low Voltage				30%V _{DD}	

Table 9. LVPECL DC Electrical Characteristics

 V_{DD} = 3.3V, 2.5V, 1.8V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C. Below are guaranteed for listed standard frequencies.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
		$V_{DD} = 3.3V \pm 5\%$.	1.85		2.3	
V _{OH}	Output High Voltage	V _{DD} = 2.5V ±5%.	1.1		1.45	
		V _{DD} = 1.8V ±5%.	0.5		0.8	
	Output Low Voltage	$V_{DD} = 3.3V \pm 5\%$.	1.1		1.65	V
V_{OL}		$V_{DD} = 2.5V \pm 5\%$.	0.35		0.85	V
		V _{DD} = 1.8V ±5%.	0		0.25	
V _{IH}	Enable/Disable Input High Voltage		70%V _{DD}			
V _{IL}	Enable/Disable Input Low Voltage				30%V _{DD}	



Table 10. HCSL DC Electrical Characteristics

 V_{DD} = 3.3V, 2.5V, 1.8V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C. Below are guaranteed for listed standard frequencies.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units	
		$V_{DD} = 3.3V \pm 5\%$.	0.6		1.1		
V _{OH}	Output High Voltage	$V_{DD} = 2.5V \pm 5\%$.	0.55		0.95		
			V _{DD} = 1.8V ±5%.	0.45		0.7	V
V _{OL}	Output Low Voltage		0		0.2	V	
V _{IH}	Enable/Disable Input High Voltage		70%V _{DD}				
V _{IL}	Enable/Disable Input Low Voltage				30%V _{DD}		

Table 11. LVCMOS DC Electrical Characteristics

 V_{DD} = 3.3V, 2.5V, 1.8V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C. Below are guaranteed for listed standard frequencies.

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V _{OH}	Differential Output Voltage		90%V _{DD}			
V_{OL}	Output Offset Voltage				10%V _{DD}	V
V _{IH}	Enable/Disable Input High Voltage		70%V _{DD}			V
V _{IL}	Enable/Disable Input Low Voltage				30%V _{DD}	



AC Electrical Characteristics

Table 12. 3.3V AC Electrical Characteristics

 V_{DD} = 3.3V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Т	est Condition	Minimum	Typical	Maximum	Units
		LVDS.		0.016		1500	
F	Output Frequency Range	LVPECL, HCSL.		0.016		670	MHz
		LVCMOS.		0.016		167	
		Temperature = -2	0°C to +70°C.	±20		±100	ppm
	Frequency Stability	Temperature = -4	0°C to +85°C.	±25		±100	ppm
		Temperature = -4	0°C to +105°C.	±50		±100	ppm
	Aging (1st year)	T _A = 25°C.				±3	
	Aging (10 years)	T _A = 25°C.				±10	
		LVDS.	Differential.		100		
	Output Load	LVPECL.	V _{DD} - 2.0V.		50		Ω
	Output Load	HCSL.	To GND.		50		
		LVCMOS.	To GND.		15		pF
T _{ST}	Start-up Time	Output valid time specified level.	after V _{DD} meets minimum			10	ms
	Output Rise Time	LVDS.			275	380	
4		LVPECL.	20% to 80% Vpk-pk.			400	ps
t _R		HCSL.				330	
		LVCMOS.	10% to 90% V _{DD.}			3	ns
		LVDS.			275	380	ps
4	Output Fall Time	LVPECL.	80% to 20% Vpk-pk.			400	
t _F	Output Fail Time	HCSL.				330	
		LVCMOS.	90% to 10% V _{DD.}			3	ns
		LVDS.		45		55	
		LVPECL.	F _{OUT} ≤ 312.5MHz.	45		55	
O _{DC}	Output Clock Duty Cycle	LVI LOL.	F _{OUT} > 312.5MHz.	40		60	%
ODC	Output Glock Duty Cycle	HCSL.		45		55	70
		LVCMOS.	F _{OUT} ≤ 62.5MHz.	45		55	
		EVOIVIOS.	F _{OUT} > 62.5MHz.	40		60	
T_{OE}	Output Enable/ Disable Time					100	ns
		LVDS.			300	400	
f.,,	Phase Jitter	LVPECL.			300	400	fsec
f _{JITTER}	(12kHz–20MHz)	HCSL.			300	400	1000
		LVCMOS.	F _{OUT} = 100MHz.		300	400	



Table 13. 2.5V AC Electrical Characteristics

 V_{DD} = 2.5V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test Condition		Minimum	Typical	Maximum	Units
		LVDS.		0.016		1350	
F Output Frequency Range	LVPECL.		0.75		670	N A 1 1_	
F	Output Frequency Range	HCSL.		0.016		670	MHz
		LVCMOS.		0.016		167	
		Temperature = -2	0°C to +70°C.	±20		±100	ppn
	Frequency Stability	Temperature = -4	0°C to +85°C.	±25		±100	ppr
		Temperature = -4	0°C to +105°C.	±50		±100	ppr
	Aging (1st year)	T _A = 25°C.				±3	
	Aging (10 years)	T _A = 25°C.				±10	
		LVDS.	Differential.		100		
	Output Load	LVPECL.	V _{DD} - 2.0V.		50		Ω
	Output Load	HCSL.	To GND.		50		
		LVCMOS.	To GND.		15		pl
T _{ST}	Start-up Time	Output valid time after V _{DD} meets minimum specified level.				10	m
t _R Output Rise Time		LVDS.			300	400	
	Outrat Dia a Tima	LVPECL.	20% to 80% Vpk-pk.		250	630	p:
	Output Rise Time	HCSL.				315	
		LVCMOS.	10% to 90% V _{DD.}			3	n
		LVDS.			300	400	
1	Outrot Fall Times	LVPECL.	80% to 20% Vpk-pk.		360	630	p:
t _F	Output Fall Time	HCSL.				315	
		LVCMOS.	90% to 10% V _{DD} .			3	n
		LVDS.	•	45		55	
		LVDECL	F _{OUT} ≤ 156.25MHz.	45		55	
O _{DC} Outp	Output Clock Duty Cycle	LVPECL.	F _{OUT} ≤ 156.25MHz.	40		60	0/
	Output Clock Duty Cycle	HCSL.	<u>'</u>	45		55	%
		LVCMCS	F _{OUT} ≤ 62.5MHz.	45		55	
		LVCMOS. $F_{OUT} > 62.5 MHz.$		40		60	
T _{OE}	Output Enable/ Disable Time					100	ns
		LVDS.			400	500	
	Phase Jitter	LVPECL.			350	500	t
JITTER	(12kHz–20MHz)	HCSL.			350	500	fse
		LVCMOS.	F _{OUT} = 100MHz.		350	500	



Table 14. 1.8V AC Electrical Characteristics

 V_{DD} = 1.8V ±5%, T_A = -20°C to +70°C; -40°C to +85°C, -40°C to +105°C.

Symbol	Parameter	Test Condition		Minimum	Typical	Maximum	Units
		LVDS.		0.016		1000	
F Output Frequency Range	LVPECL, HCSL.		0.016		670	MHz	
		LVCMOS.		0.016		125	
		Temperature = -20°0	C to +70°C.	±20		±100	ppm
	Frequency Stability	Temperature = -40°0	C to +85°C.	±25		±100	ppm
		Temperature = -40°0	C to +105°C.	±50		±100	ppm
	Aging (1st year)	T _A = 25°C.				±3	
	Aging (10 years)	T _A = 25°C.				±10	
		LVDS.	Differential.		100		Ω
	Output Load	LVPECL, HCSL.	To GND.		50		12
		LVCMOS.	To GND.		10		pF
T _{ST}	Start-up Time	Output valid time after specified level.	er V _{DD} meets minimum			10	ms
t _R Output Rise Time	LVDS.			250	315		
	Output Rise Time	LVPECL.	20% to 80% Vpk-pk.		250	350	ps
		HCSL.				320	
		LVCMOS.	10% to 90% V _{DD.}		5		ns
	t _F Output Fall Time	LVDS.			250	315	
		LVPECL.	80% to 20% Vpk-pk.		250	350	ps
ιĘ		HCSL.				320	
		LVCMOS.	90% to 10% V _{DD.}		5		ns
		LVDC	F _{OUT} ≤ 156.25MHz.	45		55	
		LVDS.	F _{OUT} ≤ 156.25MHz.	40		60	
		LVPECL.	F _{OUT} ≤ 312.5MHz.	45		55	
O_DC	Output Clock Duty Cycle	LVPEGL.	F _{OUT} > 312.5MHz.	40		60	%
		HCSL.		40		60	
		LVCMOS.	F _{OUT} ≤ 62.5MHz.	45		55	
		LVCIVIOS.	F _{OUT} > 62.5MHz.	40		60	
T _{OE}	Output Enable/ Disable Time					100	ns
		LVDS.			800	1200	
f	Phase Jitter	LVPECL.			750	1200	feed
f _{JITTER}	(12kHz–20MHz)	HCSL.			100	1200	fsec
		LVCMOS.	F _{OUT} = 100MHz.		800	1200	



Notes for all AC Electrical Characteristics tables:

12C Bus Characteristics

Table 15. I2C Bus DC Characteristics

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V _{IH}	Input High Level	_	0.7 × V _{DD33}	_	_	V
V_{IL}	Input Low Level	_	_		$0.3 \times V_{DD33}$	V

Table 16. I2C Bus AC Characteristics

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
F _{SCLK}	Serial Clock Frequency (SCL)	_	_	100	400	kHz
t _{BUF}	Bus Free Time between STOP and START	_	1.3	_	_	μs
t _{SU:START}	Setup Time, START	_	0.6	_	_	μs
t _{HD:START}	Hold Time, START	_	0.6	_	_	μs
t _{SU:DATA}	Setup Time, Data Input (SDA)	_	100	_	_	μs
t _{HD:DATA}	Hold Time, Data Input (SDA) ¹	_	0	_	_	μs
t _R	Rise Time, Data and Clock (SDA, SCL)		_	_	300	ns
t _F	Fall Time, Data and Clock (SDA, SCL)	_	_	_	300	ns
t _{HIGH}	High Time, Clock (SCL)	_	0.6	_	_	μs
t_{LOW}	Low Time, Clock (SCL)	_	1.3	_	_	μs
t _{SU:STOP}	Setup Time, STOP	_	0.6	_	_	μs

¹ A device must internally provide a hold time of at least 300ns for the SDA signal (referred to the V_{IH(MIN)} of the SCL signal) to bridge the undefined region of the falling edge of SCL.

 $^{^{1}}$ A pull-up resistor from V_{DD} to E/D enables output when pin 1 is left open.

² Installation should include a 0.01µF bypass capacitor placed between VDD and GND to minimize power supply line noise.

³ Stability is inclusive of 25°C tolerance, operating temperature range, input voltage change, load change, aging, shock and vibration.

⁴ Standard LVCMOS frequencies include 10MHz, 12MHz, 12.288MHz, 16MHz, 20MHz, 24MHz, 24.576MHz, 25MHz, 33.333MHz, 40MHz, 48MHz, 50MHz, 100MHz, 125MHz and 156.25MHz.

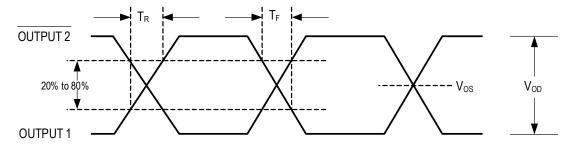
⁵ Standard differential frequencies include 100MHz, 106.25MHz, 125MHz, 150MHz, 155.52MHz, 156.25MHz, 200MHz, 212.5MHz, 250MHz, 300MHz, 312.5MHz and 400MHz.



Output Waveforms

Figure 1. LVDS Output Waveforms

Output Levels/Rise Time/Fall Time Measurements



Oscillator Symmetry

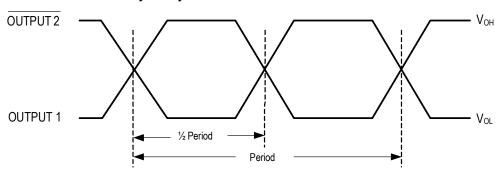
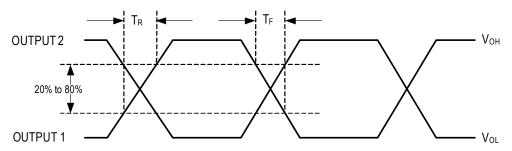


Figure 2. LVPECL Output Waveforms

Rise Time/Fall Time Measurements



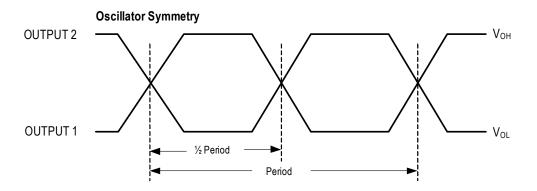
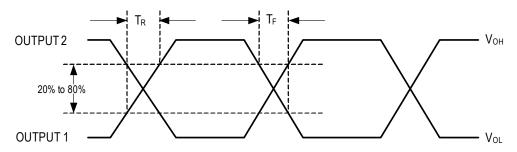




Figure 3. HCSL Output Waveforms

Rise Time/Fall Time Measurements



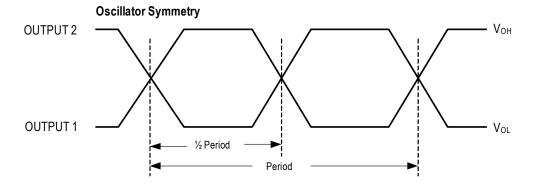
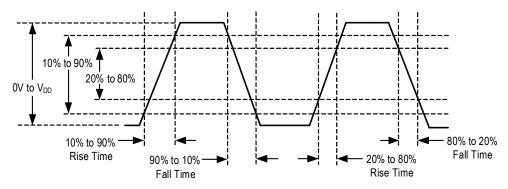
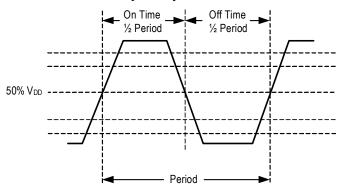


Figure 4. LVCMOS Output Waveforms

Rise Time/Fall Time Measurements



Oscillator Symmetry



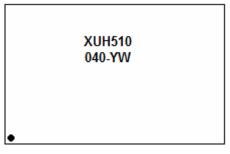


Package Outline Drawings

The package outline drawings (JS6, JU6) are appended at the end of this document. The package information is the most current data available.

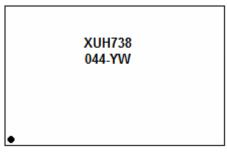
Marking Diagrams

JS6 5.0 × 3.2 mm Package Option (example based on XUH510040.0000001)



- Line 1:
 - "XU" = family; "H" = output type; "5" = package size; "1" = voltage; "0" = precision level. This number will vary depending upon the output type, voltage, and precision values selected in the orderable part number.
- Line 2:
 - "040" denotes last three digits to the left of the decimal point as shown in the above example. This number will vary depending upon the frequency value selected in the orderable part number.
 - "YW" denotes the last digit of the year and work week the part was assembled.

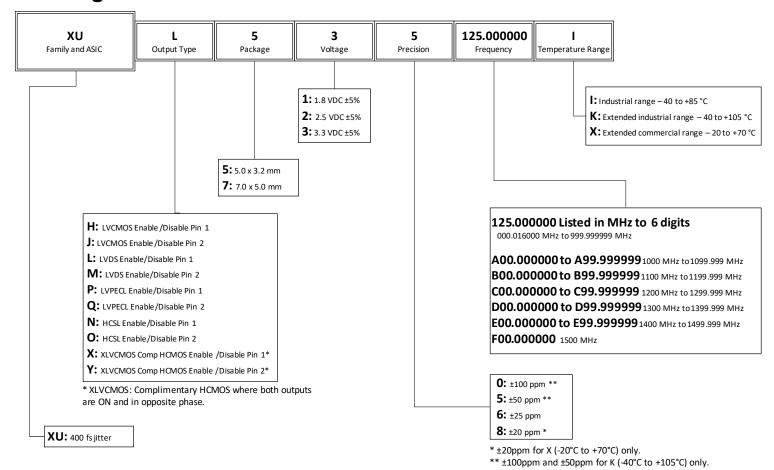
JU6 7.0 × 5.0 mm Package Option (example based on XUH738044.736000X)



- Line 1:
 - "XU" = family; "H" = output type; "7" = package size; "3" = voltage; "8" = precision level. This number will vary depending upon the output type, voltage, and precision values selected in the orderable part number.
- Line 2:
 - "044" denotes last three digits to the left of the decimal point as shown in the above example. This number will vary depending upon the frequency value selected in the orderable part number.
 - "YW" denotes the last digit of the year and work week the part was assembled.



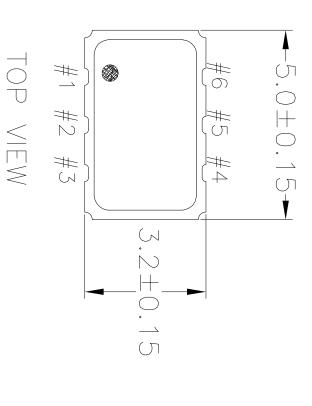
Ordering Information

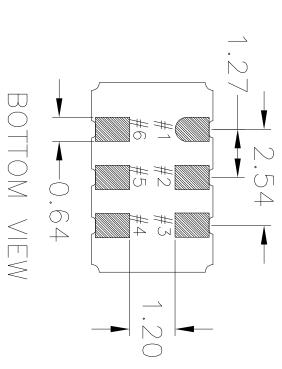




Revision History

Revision Date	Description of Change
January 19, 2021	 Removed 4-pin package description table, figure, and package drawing references. Added footnote for pin 5 in Table 1. Added footnote under "Output Type" in Ordering Information.
January 12, 2021	Added Marking Diagrams section and updated Package Outline Drawings links.
February 11, 2020	Added I2C Bus Characteristics tables.
June 28, 2019	Added footnote to frequency range bullet under front page Features.
June 25, 2018	Updated Package Outline Drawings section.
November 22, 2017	 Updated Theta JA and JB in Absolute Maximum Ratings table. Added MSL statement under Mechanical Testing table. Updated ordering information.
October 19, 2017	 Updated document title. Updated Features bullets. Updated Absolute Maximum Ratings and ESD Compliance tables. Added -40°C to +105°C rating to all electrical tables. Removed phase noise charts. Updated Ordering Information table.
May 12, 2017	 Reformatted embedded tables. Removed "Jitter Performance" tables and moved the "Phase Jitter (12kHz–20MHz)" parameter to its respective AC Electrical Characteristics table. Updated all Output Waveform drawings.
December 1, 2016	Initial release.





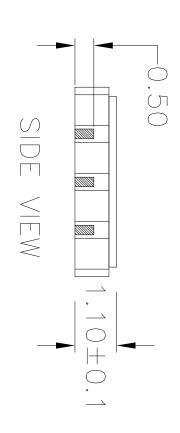
00 PEV 01 03 03

REVISIONS
DESCRIPTION
INITIAL RELEASE
ADDED LID IN TOP VIEW
UPDATED LID TOLERANCES
UPDATE PACKAGE DRAWING

04/2/12 07/12/12 12/03/12 8/8/14

J.HUA PP

APPROVED



NOTES:

1. ALL DIMENSIONS IN MM.

			CHECKED	DRAWN RAC 04/2/12	APPROVALS	XXXX	××+	DECIMAL	UNLESS SPECIFIED
				04/2/12	DATE		+	ANGULAR	SIFIED
DO NO	С	SIZE			TITLE	W	4	M	
DO NOT SCALE DRAWING	PSC-4411	DRAWING No.	1.1 mm Thick	5.0 x 3.2 mm BODY	TITLE JS6 PACKAGE OUTLINE	www.IDT.com			
				¥	Ē	AX: (408	HONE: (4	san Jose,	3024 Silve
SHEET						FAX: (408) 492-8674	PHONE: (408) 727-6116	San Jose, CA 95138	6024 Silver Creek Valley Rd
SHEET 1 OF 2	03	REV				74	6116	00	Valley Rd
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ADDED LID IN TOP VIEW
UPDATED LID TOLERANCES
UPDATE PACKAGE DRAWING

04/2/12 07/12/12 12/03/12 8/8/14

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REVISIONS
DESCRIPTION
INITIAL RELEASE

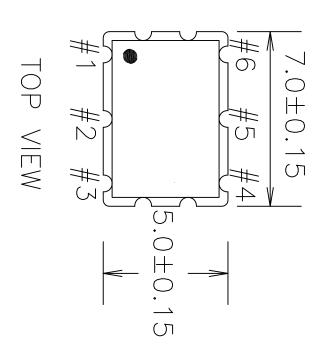
DATE

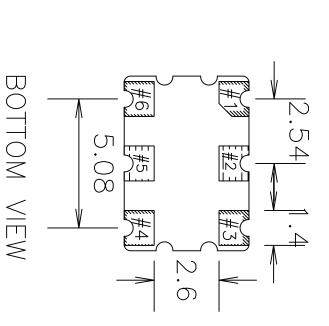
APPROVED

RECOMMENDED LAND PATTERN

- ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
 TOP DOWN VIEW. AS VIEWED ON PCB.
 COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
 LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 LAND PATTERN RECOMMENDATION PER IPC—7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

WWW.IDT.com FHONE: (40) TE NTLE JS6 PACKAGE OUTLINE 5.0 x 3.2 mm BODY 1.1 mm Thick SZE DRAWING No. DO NOT SCALE DRAWING			
WWW.IDT.com FAX: (408) TITLE JS6 PACKAGE DUTLINE 5.0 x 3.2 mm BODY 1.1 mm Thick SIZE DRAWNG No. C PSC-4411 DO NOT SCALE DRAWNG		DRAWN RAC CHECKED	SS SPEC
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Jose, Jelle: (408)	DO NO	SIZE	
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¥ # ♡ ▶ (ş	3 F	6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727–6116 FAX: (408) 492–8674
CA 95138 08) 727-6116 492-8674 REV 03 SHEET 2 0F 2	IEET 2		727-61 32-8674
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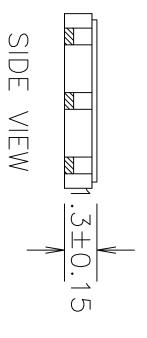


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REVISIONS
DESCRIPTION
INITIAL RELEASE
UPDATE PACKAGE DRWING

10/5/12 8/12/14

J.HUA ß



NOTES:

1. ALL DIMENSIONS IN MM.

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				10/03/12	DATE		CIFIED ANGULAR
DO NO	С	SIZE			ᆵ	\$	
DO NOT SCALE DRAWING	PSC=4430	DRAWING No.	1.3 mm Thick	7.0 x 5.0 mm BODY	JU6 PACKAGE OUTLINE	WWW.IDT.com FAX: (408)	Tal 6024 Silve San Jose, PHONE: (4
SHEET 1 OF 2						FAX: (408) 492-8674	6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727-6116
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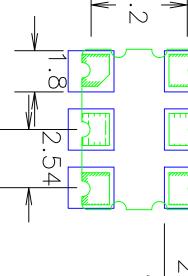
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REVISIONS
DESCRIPTION
INITIAL RELEASE
UPDATE PACKAGE DRWING

APPROVED KS J.HUA

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RECOMMENDED LAND PATTERN

- 1. ALL DIMENSION ARE IN mm. ANGLES IN DEGREES.
 2. TOP DOWN VIEW. AS VIEWED ON PCB.
 3. COMPONENT OUTLINE SHOW FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

		CHECKED	DRAWN XL	APPROVALS	UNLESS SPECIFIED DECIMAL ANGU XX± ± XXXX± XXXXX±
			10/03/12	DATE	CIFIED ANGULAR ±
DO N	SIZE			III.E	§ (1)
DO NOT SCALE DRAWING	PSC-4430	1.3 mm Thick	7.0 x 5.0 mm BODY	JU6 PACKAGE OUTLINE	Tix 6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 727–6116 WWW.IDT.COM FAX: (408) 492–8974
SHEET					r Creek 1 CA 9513 CB) 727- 08) 727- 0492-86
SHEET 2 OF 2	REV 01				Valley Rd 8 6116 74

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